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- **Members of the Texas Instruments** Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes **PCB Layout**
- Distributed V<sub>CC</sub> and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **EPIC™** (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

#### description

The 'ACT16541 are noninverting 16-bit buffers composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the two output-enable  $(1\overline{OE1}$  and  $1\overline{OE2}$ or 20E1 and 20E2) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

**54ACT16541...WD PACKAGE** 74ACT16541 . . . DL PACKAGE (TOP VIEW)

			_		1
1 <del>OE1</del>	_		U	48	1 <del>0E</del> 2
1Y1	$Q_2$	2		47	] 1A1
1Y2		3		46	]1A2
GND		ļ		45	GND
1Y3		5		44	1A3
1Y4		6		43	]1A4
$V_{CC}$	[] 7	7		42	$]v_{cc}$
1Y5				41	] 1A5
1Y6		)		40	]1A6
GND				39	GND
1Y7				38	] 1A7
1Y8	[] 1	2		37	] 1A8
2Y1	[] 1	3		36	]2A1
2Y2				35	2A2
GND	[] 1	5		34	GND
2Y3	[] 1	6		33	2A3
2Y4	[] 1	7		32	2A4
$V_{CC}$	[] 1	8		31	]v <sub>cc</sub>
2Y5	[] 1	9		30	2A5
2Y6				29	2A6
GND	<b>Q</b> 2	21		28	GND
2Y7	<b>Q</b> 2	22		27	2A7
2Y8		23		26	2A8
20E1		24		25	2 <mark>0E</mark> 2
	_				,

The 74ACT16541 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16541 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16541 is characterized for operation from -40°C to 85°C.

#### **FUNCTION TABLE** (each 8-bit section)

	INPUTS		OUTPUT
OE1	OE2	Α	Υ
L	L	L	L
L	L	Н	Н
Н	X	Χ	Z
Х	Н	Χ	Z

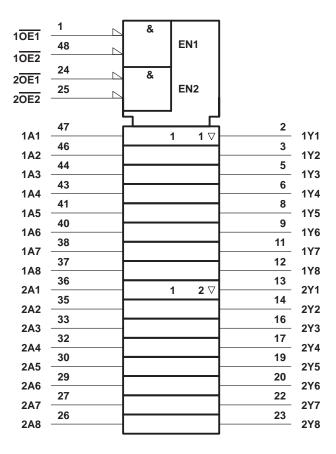


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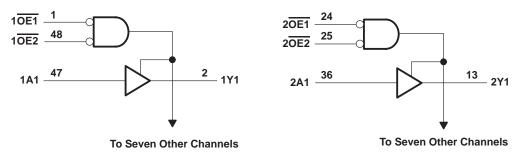


## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±400 mA
Maximum package power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2): DL package	e 1.2 W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

		54ACT16541		41	74	11	UNIT	
		MIN	MIN NOM MAX MIN NOM		NOM	MAX		
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		7	2			V
V <sub>IL</sub>	Low-level input voltage		Ś	0.8			0.8	V
٧ <sub>I</sub>	Input voltage	0	200	VCC	0		VCC	V
Vo	Output voltage	0	1	VCC	0		VCC	V
IOH	High-level output current		3	-24			-24	mA
lOL	Low-level output current	, O.	7	24			24	mA
Δt/Δν	Input transition rise or fall rate	8		10	0		10	ns/V
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils.

## 54ACT16541, 74ACT16541 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUPUTS

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST COMPLTIONS	,,	T,	4 = 25°C	54ACT16541	74ACT16541	UNIT
PARAMETER	TEST CONDITIONS	vcc	MIN	TYP MAX	MIN MAX	MIN MAX	UNII
	Jan - 50 uA	4.5 V	4.4		4.4	4.4	
	I <sub>OH</sub> = -50 μA	5.5 V	5.4		5.4	5.4	
Voн	10.1 - 24 mA	5.5 V	3.9		3.8	3.8	V
	I <sub>OH</sub> = -24 mA	5.5 V	4.94		4.8	4.8	
	I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V			3.85	3.85	
	I <sub>OL</sub> = 50 μA	4.5 V		0.1	0.1	0.1	V
	ΙΟΣ = 30 μΑ	5.5 V		0.1	0.1	0.1	
VOL	le: - 24 mA	4.5 V		0.36	0.44	0.44	
	I <sub>OL</sub> = 24 mA	5.5 V		0.36	0.44	0.44	
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V			1.65	1.65	
lį	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V		±0.1	±1	±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V		±0.5	±5	±5	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		8	80	80	μΑ
∆l <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V		0.9	1	1	mA
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V		4			pF
Со	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V		13			pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T <sub>A</sub> = 25°C			54ACT16541		74ACT16541		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t <sub>PLH</sub>	Α	V	3.1	5.9	7.9	3.1	9	3.1	9	no
t <sub>PHL</sub>	A	Ĭ	2.7	6.3	8.3	2.7	9.2	2.7	9.2	ns
<sup>t</sup> PZH	<del></del>	V	2.8	6.5	8.9	2.8	9.7	2.8	9.7	ns
<sup>t</sup> PZL	OE	ı	3.5	7.5	9.9	3.5	11	3.5	11	115
t <sub>PHZ</sub>	ŌĒ	V	4.5	8.5	10.3	4.5	11.3	4.5	11.3	ns
t <sub>PLZ</sub>	J OE	Y	4.9	8	9.9	4.9	10.7	4.9	10.7	

## operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

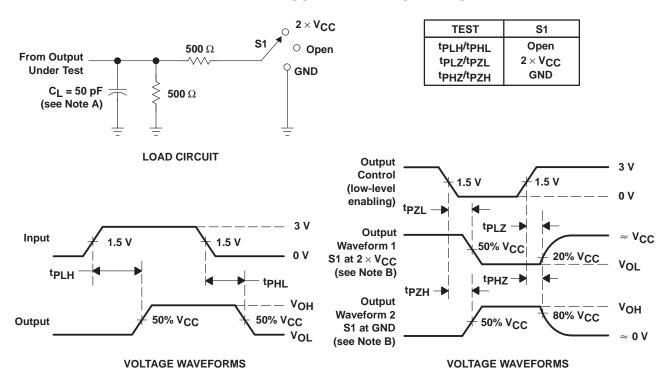
	PARAMETER	TEST CO	TYP	UNIT		
C <sub>pd</sub>	Power discinction conscitance per huffer/driver	Outputs enabled	C <sub>I</sub> = 50 pF,	f = 1 MHz	40	pF
	Power dissipation capacitance per buffer/driver	Outputs disabled	CL = 50 pr,	I = I IVITZ	9.5	



<sup>&</sup>lt;sup>‡</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3$  ns,  $t_f = 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
74ACT16541DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16541	Samples
74ACT16541DLG4	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16541	Samples
74ACT16541DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16541	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

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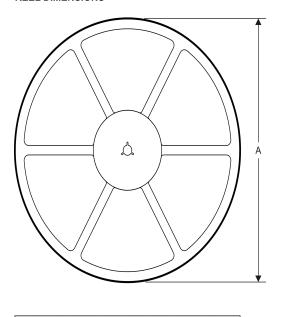
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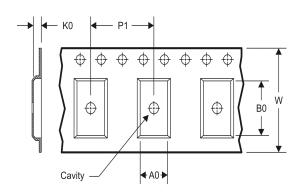
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## TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**



#### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### TAPE AND REEL INFORMATION

#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16541DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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#### \*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	74ACT16541DLR	SSOP	DL	48	1000	367.0	367.0	55.0	

## DL (R-PDSO-G48)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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